CS INTERNATIONAL CONFERENCE

2026 AGENDA

Correct as of 06-May-2026 12:15pm
For the latest version of our agenda, visit csinternational.net

Day 1 - Monday 20th April 2026

11:00	**AngelTech Innovate Summit - Limited places! Requires separate registration: https://www.angeltech-innovate.net/register**
18:00	Pre-conference Networking Drinks / Dinner Reception (available to those who have registered for 21st & 22nd April for AngelTech Conference)

Day 2 - Tuesday 21st April 2026

08:00 Registration and welcome refreshments

08:50 Housekeeping by Chris Meadows and Tim Bettles - Conference Chairs

Growing Revenues in GaN Power Electronics

09:00 Radiation Hardened High Voltage GaN Technology to Enable a Permanent Human Presence on the Moon and Beyond
Presented by Antxon Arrizabalaga - Semi Zabala

09:15 Advancing GaN Power Technologies: Scaling to 300 mm for the AI Era
Presented by Pierre Gassot - imec

09:30 Analytical X-Ray Solutions for Thin Film and Wafer Analysis
Presented by Andrey Zameshin - Malvern Panalytical

09:45 Leading Epitaxy Solutions for High Volume Manufacturing of Compound Semiconductor & Optoelectronic Devices
Presented by Dr. Nicolas Muesgens - Aixtron

10:00 D3GaN Power Modules for Automotive Inverters Achieving 99.7% WLTP Efficiency
Presented by Dieter Liesabeths - VisIC Technologies

10:15 GaN Comes of Age: From Fast Chargers to Strategic Power Platforms
Presented by Roy Dagher - Yole Group

10:30 Morning Break - Refreshments & Networking

11:00 Improving GaN with a Dash of Oxygen
Presented by Robert Mears - Atomera

11:15 Chemical Vapor Deposition of Nitrides by Carbon-free Precursors
Presented by Stefano Leone - Fraunhofer Institute IAF

11:30 Revelios: Semi-Automated, Non-Destructive Crystalline Defect Metrology for GaN-Based Epitaxial Layers
Presented by Martin ?alkovsky - Thermofisher

11:45 Tunable Epi System for RF GaN HEMT
Presented by Ray (Dongsik) Suh - TES Co. Ltd

12:00 High Performance GaN Power Devices Enabled by Wafer Bonding
Presented by Elisabeth Brandl - EV Group

12:15 Accelerating GaN Process Development through Modeling: from Recipe to Device Characteristics
Presented by Andrey Smirnov - STR

12:30 WiseGan Gen2: Integrated GaN SiP Unlocking New Power Architectures with Digital Control
Presented by Ridha Hamza - Wise Integration

12:45 Lunch Break & Networking

14:15 Startup Elevator Presentations

Revitalising the SiC industry

14:25 Quantifying What Matters in SiC Fabs: Inline TXRF, HRXRD, and XRR for Yield Control
Presented by Frank Hofmann - Rigaku

14:40 Further Growth Opportunities for SiC in New Application Fields
Presented by Peter Friedrichs - Infineon

14:55 Enhancing Yield in Compound Semiconductor Processing
Presented by Serge Jedwab - Siconnex

15:10 SiC: The Trusted Partner and Growth Engine for the High-Power Conversion Industry
Presented by Mrinal K. Das - onsemi

15:25 Afternoon Break and Networking

16:10 Advanced Metrology Strategies for High-Yield SiC Manufacturing in Mature and Emerging Power Markets
Presented by Tamzin Lafford - Bruker UK

16:25 Electrical Parametric Characterization of Wide-Bandgap Semiconductor Wafers and Devices
Presented by Maarten Raimond - Tektronix

16:40 RAITH VECTOR in Compound Semiconductors
Presented by Jean-Claude Menard - Raith

16:55 3 Decades of SiC Innovation Leading to 200 mm Production and Full Vertical Integration
Presented by Manuel Gärtner - STMicroelectronics

17:10 Closing Remarks

18:00 Networking Drinks and Dinner Reception (concludes around 20:00)

18:30 AngelTech Rump Session - Bottlenecks & Battlegrounds: The Future of the AI Chip Ecosystem
Presented by David Cheskis - Square Zero Technologies, and Diana Khlan - Chips Weekly

Day 3 - Wednesday 22nd April 2026

08:00 Registration and welcome refreshments

08:50 Housekeeping by Conference Chairs

Advancing a broadening laser portfolio

09:00 **Development of Strain-compensated Distributed Bragg Reflectors for GaN-based VCSELs With Potential for Faster Growth and Higher Productivity**
Presented by Takeshi Kawashima - Ricoh

09:15 **Unlocking the Future: Nanoporous Compound Semiconductor Technology for Next-Gen Sensing, Digital Health and Energy-Efficient Data Centers Optical Interconnect**
Presented by Jung Han - InPHRED

09:30 **Manufacturing VCSELs on 150mm and 200mm Wafer Formats**
Presented by Peter Smowton - Cardiff University

09:45 **Enabling As/P Epitaxy at Scale for Photonics, Optoelectronics, and Solar**
Presented by Vinod Merai - Veeco

10:00 **Advanced Volume Manufacturing InP Etching on 150 mm Wafers Using High Temperature and Reliability Electrostatic Chuck**
Presented by Zhanxiang Zhao - Oxford Instruments

10:15 **Developments in Surface Emitting Lasers and Component technologies**
Presented by Graham Berry - Huawei Bragg Research Center (UK)

10:30 **Photonic Crystal Surface Emitting Lasers – Their Potential for Advanced Communications**
Presented by Richard Taylor - Vector Photonics

10:45 Morning Break - Refreshments & Networking

microLEDs: How to gain market traction

11:15 **From Display to System: Enabling System-on-Panel Architectures Using MicroLEDs and MicroSolid Printing™**
Presented by Reza Chaji - VueReal

11:30 **Scalable MicroLED Optical Link Prototype Fabrication for the Next Generation Computing**
Presented by Vygintas Jankus - CEA-Leti

11:45 **Building a Silicon Fab-Compatible Supply Chain for MicroLED Manufacturing**
Presented by Alexander Loesing - Allos Semiconductors

12:00 Lunch Break & Networking

Unlocking the potential of ultra-wide bandgap materials

13:30 **Gallium Oxide RF Electronics: Recent Advances Toward Unlocking UWBG Potential**
Presented by Min Zhou - Xidian University

13:45 **12" SiC – Wafering Solutions for AR and Advanced Packaging**
Presented by Malte Mueller - Lapmaster Wolters

14:00 **High Voltage Power Technology with Gallium Oxide and AlGaN**
Presented by Martin Kuball - University of Bristol

14:15 **Towards More Efficient Power Transistors: Modulation-Doped β-(Al_xGa_{1-x})$_2O_3$/Ga_2O_3 Heterostructures with Enhanced Electron Mobility**
Presented by Andreas Fiedler - Leibniz-Institut für Kristallzüchtung (IKZ)

14:30 **A Soft-Switching-Based Inverter Topology for High-Efficiency Applications**
Presented by Ajay Poonjal Pai - Sanan

14:45 **Gallium Oxide from Epitaxy to Device Demonstration - A Holistic Approach to Ultra-Wide Bandgap Power Electronics**
Presented by Saptarsi Ghosh - Swansea University

15:00 Closing Remarks

NOTES